

2017 IUS



2017 IEEE INTERNATIONAL ULTRASONICS SYMPOSIUM



WASHINGTON, D.C., USA

September 6-9, 2017



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ABSTRACT SUBMISSION NOW OPEN

Deadline for abstract submissions: April 1st, 2017.

The 2017 IEEE International Ultrasonics Symposium will be held at the **Omni Shoreham Hotel, Washington, D.C., USA, from September, 6-9, 2017.** Oral and poster presentation formats will be used. Papers are solicited for this conference describing original work in the field of Ultrasonics from the following subject classifications:

Group 1: Medical Ultrasonics

MBB Medical Beamforming and Beam Steering

MBE Biological Effects & Dosimetry

MBF Blood Flow Measurement

MCA Contrast Agents

MEL Elastography

MIM Medical Imaging

MPA Medical Photoacoustics

MSD System & Device Design

MSP Medical Signal Processing

MTC Medical Tissue Characterization

MTH Therapeutics, Hyperthermia, and Surgery

Group 2: Sensors, NDE & Industrial Applications

NAF Acoustic Microfluidics

NAI Acoustic Imaging

NAM Acoustic Microscopy

NAS Acoustic Sensors

NDE General NDE Methods

NEH Energy Harvesting

NFM Flow Measurement

NMC Material & Defect Characterization

NPA Photoacoustics

NPC Process Control

NSP Signal Processing

NTD Transducers: NDE and Industrial

NUA Underwater Acoustics

NWP Wave Propagation

Group 3: Physical Acoustics

PAT Acoustic Tweezers and Particle Manipulation

PNL Nonlinear Acoustics

PGP General Physical Acoustics

PTE High Performance and Temperature Effects

POA Opto-acoustics

PPN Phononics

PTF Thin Films

PMI Modeling and Inversion

PUM Ultrasonic Motors & Actuators

PNR Non-Reciprocal Acoustics

Group 4: Microacoustics: SAW, FBAR, MEMS

ADA Device Applications

ADD Device Design

ADM Device Modeling

AMP Materials & Propagation

AMR Microacoustic Resonators

AMS Microacoustic Sensor Devices & Apps.

ATR Tunable & Reconfigurable Devices

Group 5: Transducers & Transducer Materials

TMC Materials Fabrication and Characterization

TMO Modeling (Analytical & Numerical)

TFT Thin and Thick Piezoelectric Films

TMU Micromachined Ultrasonic Transducers

TMI Biomedical Diagnostic and Imaging Transducers

TTT Biomedical Therapeutic Transducers

THF Front-end and Integrated Electronics

TFI High Frequency Transducers

TPF Applications of Piezoelectrics & Ferroelectrics

Sponsored by the IEEE Ultrasonics, Ferroelectrics & Frequency Control Society

SUBMISSION SYSTEM ONLINE: OPEN NOW

SUBMISSION DEADLINE: APRIL 1, 2017

ACCEPTANCE NOTIFICATION: JUNE 1, 2017

<http://ewh.ieee.org/conf/ius/2017/>